ON Semiconductor

Is Now

To learn more about onsemi™, please visit our website at
www.onsemi.com

ON Semiconductor®

FDP6030BL/FDB6030BL

N-Channel Logic Level PowerTrench® MOSFET

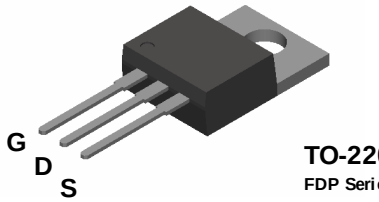
General Description

This N-Channel Logic Level MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers.

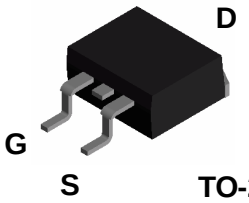
These MOSFETs feature faster switching and lower gate charge than other MOSFETs with comparable $R_{DS(on)}$ specifications resulting in DC/DC power supply designs with higher overall efficiency.

Features

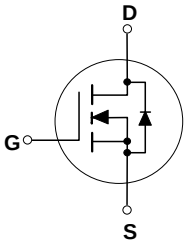
- 40 A, 30 V. $R_{DS(ON)}$ = 0.018 Ω @ V_{GS} = 10 V
  $R_{DS(ON)}$ = 0.024 Ω @ V_{GS} = 4.5 V.
- Critical DC electrical parameters specified at elevated temperature.
- Rugged internal source-drain diode can eliminate the need for an external Zener diode transient suppressor.
- High performance trench technology for extremely low $R_{DS(ON)}$.
- 175°C maximum junction temperature rating.



TO-220
FDP Series



TO-263AB
FDB Series



Absolute Maximum Ratings

T_C = 25°C unless otherwise noted

Symbol	Parameter	FDP6030BL	FDB6030BL	Units
V_{DSS}	Drain-Source Voltage	30		V
V_{GSS}	Gate-Source Voltage	±20		V
I_D	Maximum Drain Current - Continuous (Note 1)	40		A
	- Pulsed	120		
P_D	Total Power Dissipation @ T_C = 25°C	60		W
	Derate above 25°C	0.36		W/°C
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-65 to +175		°C

Thermal Characteristics

$R\theta_{JC}$	Thermal Resistance, Junction-to-Case	2.5		°C/W
$R\theta_{JA}$	Thermal Resistance, Junction-to-Ambient	62.5		°C/W

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape Width	Quantity
FDB6030BL	FDB6030BL	13''	24mm	800
FDP6030BL	FDP6030BL	Tube	N/A	45

November-2017, Rev. 3

Publication Order Number:
FDB6030BL/D

Electrical Characteristics

T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
DRAIN-SOURCE AVALANCHE RATINGS (Note 1)						
W_{DSS}	Single Pulse Drain-Source Avalanche Energy	V_{DD} = 15 V, I_D = 40 A			150	mJ
I_{AR}	Maximum Drain-Source Avalnche Current				40	A
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0 V, I_D = 250 µA	30			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I_D = 250 µA, Referenced to 25°C		23		mV/°C
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 24 V, V_{GS} = 0 V			1	µA
I_{GSSF}	Gate-Body Leakage Current, Forward	V_{GS} = 20 V, V_{DS} = 0 V			100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	V_{GS} = -20 V, V_{DS} = 0 V			-100	nA
On Characteristics (Note 1)						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = 250 µA	1	1.6	3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	I_D = 250 µA, Referenced to 25°C		-4.5		mV/°C
$R_{DS(on)}$	Static Drain-Source On-Resistance	V_{GS} = 10 V, I_D = 20 A, V_{GS} = 10 V, I_D = 20 A, T_J = 125°C V_{GS} = 4.5 V, I_D = 17 A		0.015 0.021 0.019	0.018 0.030 0.024	Ω
$I_{D(on)}$	On-State Drain Current	V_{GS} = 10 V, V_{DS} = 10 V	40			A
g_{FS}	Forward Transconductance	V_{DS} = 5 V, I_D = 20 A		30		S
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS} = 15 V, V_{GS} = 0 V, f = 1.0 MHz		1160		pF
C_{oss}	Output Capacitance			250		pF
C_{rss}	Reverse Transfer Capacitance			100		pF
Switching Characteristics (Note 1)						
$t_{d(on)}$	Turn-On Delay Time	V_{DD} = 15 V, I_D = 1 A, V_{GS} = 10 V, R_{GEN} = 6 Ω		9	17	ns
t_r	Turn-On Rise Time			11	20	ns
$t_{d(off)}$	Turn-Off Delay Time			23	37	ns
t_f	Turn-Off Fall Time			8	16	ns
Q_g	Total Gate Charge	V_{DS} = 15 V, I_D = 20 A, V_{GS} = 5 V		12	17	nC
Q_{gs}	Gate-Source Charge			3.2		nC
Q_{gd}	Gate-Drain Charge			3.7		nC
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain-Source Diode Forward Current (Note 1)				40	A
V_{SD}	Drain-Source Diode Forward Voltage	V_{GS} = 0 V, I_S = 20 A (Note 1)		0.95	1.2	V

Note:
1. Pulse Test: Pulse Width ≤ 300 µs, Duty Cycle ≤ 2.0%

Typical Characteristics

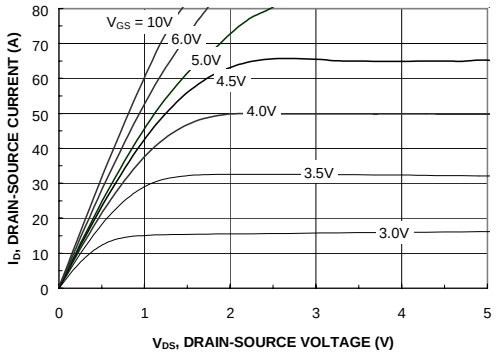


Figure 1. On-Region Characteristics.

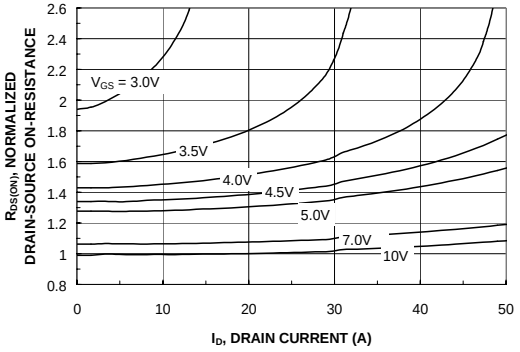


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

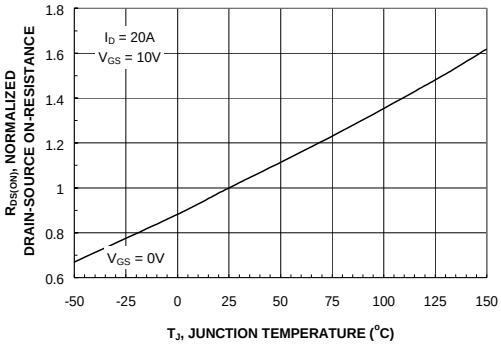


Figure 3. On-Resistance Variation with Temperature.

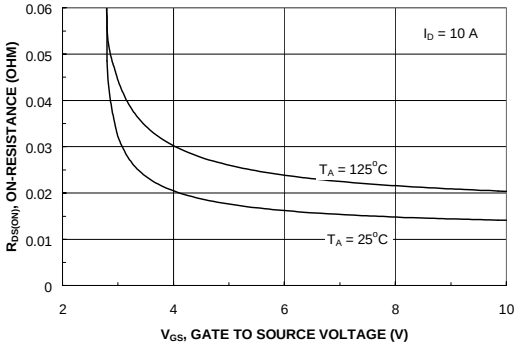


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

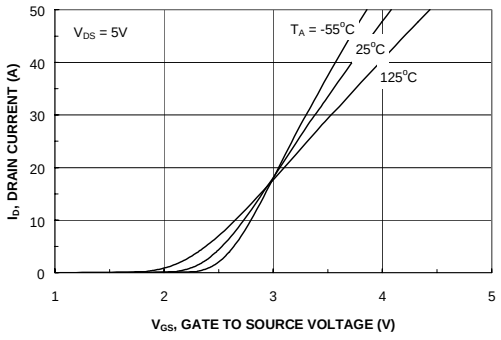


Figure 5. Transfer Characteristics.

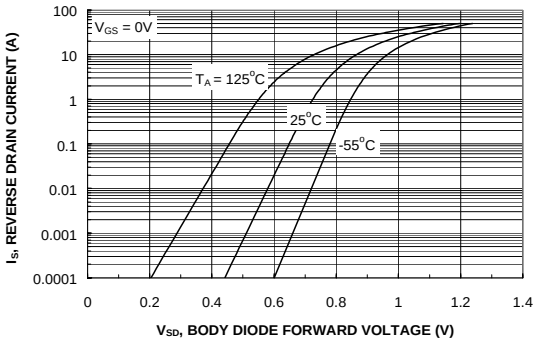


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics (continued)

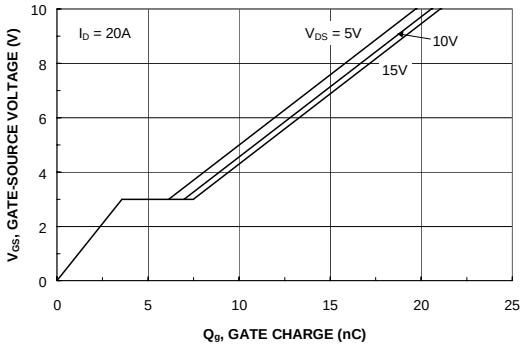


Figure 7. Gate-Charge Characteristics.

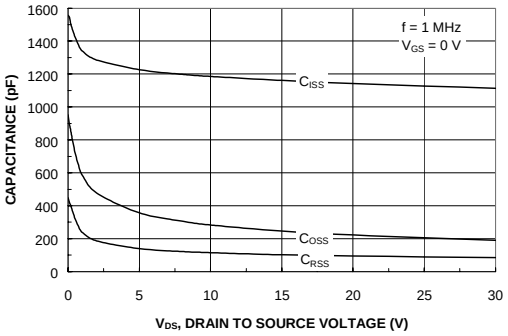


Figure 8. Capacitance Characteristics.

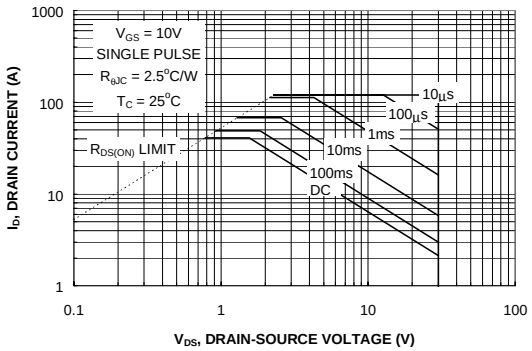


Figure 9. Maximum Safe Operating Area.

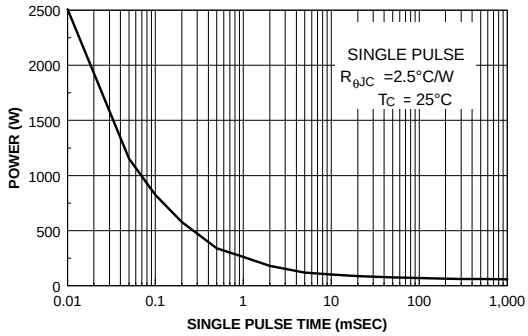


Figure 10. Single Pulse Maximum Power Dissipation.

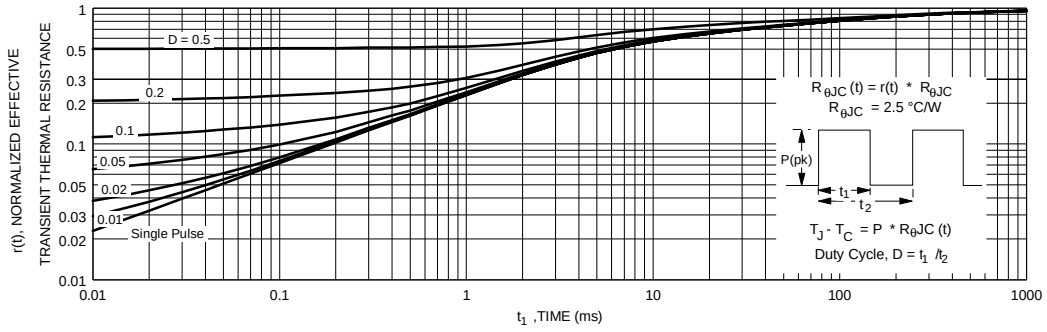


Figure 11. Transient Thermal Response Curve.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA
Phone: 303−675−2175 or 800−344−3860 Toll Free USA/Canada
Fax: 303−675−2176 or 800−344−3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800−282−9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81−3−5817−1050

ON Semiconductor Website: **www.onsemi.com**

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative